



## Material Content Data Sheet



<b>Sales Product Name</b>		IPL65R230C7		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001244948						
<b>Package</b>		PG-VSON-4-1		<b>Weight*</b>		187.65 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.621	1.93	1.93	19295	19295
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		68	
	non noble metal	zinc	7440-66-6	0.051	0.03		271	
	non noble metal	iron	7439-89-6	1.017	0.54		5420	
wire	non noble metal	copper	7440-50-8	41.300	22.01	22.59	220094	225853
	non noble metal	copper	7440-50-8	0.898	0.48	0.48	4783	4783
	encapsulation	organic material	carbon black	1333-86-4	0.220	0.12		1170
plating	plastics	epoxy resin	-	11.308	6.03		60264	
	inorganic material	silicondioxide	60676-86-0	98.262	52.36	58.51	523648	585082
	non noble metal	tin	7440-31-5	2.397	1.28	1.28	12776	12776
solder	noble metal	silver	7440-22-4	0.252	0.13	0.13	1343	1343
heatspreader	noble metal	silver	7440-22-4	0.081	0.04		433	
	non noble metal	tin	7440-31-5	0.065	0.03		347	
	non noble metal	lead	7439-92-1	3.107	1.66	1.73	16558	17338
*deviation	inorganic material	phosphorus	7723-14-0	0.008	0.00		40	
	non noble metal	zinc	7440-66-6	0.030	0.02		160	
	non noble metal	iron	7439-89-6	0.601	0.32		3205	
	non noble metal	copper	7440-50-8	24.418	13.01	13.35	130125	133530
Sum in total:						100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com